

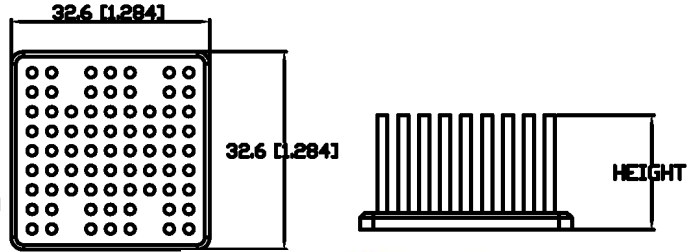
Model : MBA33005 Series

BGA Heat Sink Specification

For 33x33 Chip set



1. Material : CU1100
2. Dimension :
Foot print : 33x33mm
Height : 12, 15, 18, 21, 23, 28, 33 mm
Base (thickness) : 2.6mm



3. Finish: Antioxidant Treatment
4. Chip set package thickness and clip color
3.3+/-0.25mm - Yellow clip
1.7+/-0.25mm - Blue clip
0.8+/-0.25mm - Orange clip
5. Accessory :
Clip : Plastic (UL94-V0)
Thermal pad : T710 or others



Performance

Heat Source (LxW)	15x15
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